



- 1 Substrate: 1.59mm ± 0.18mm [0.0625" ± 0.007"]  
FR4/G10 or equivalent high temp material;  
Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish-  
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).
- 3 Solder Balls: Sn96.5Ag3.0Cu0.5

RoHS COMPLIANT

**Description:** Giga-snaP BGA SMT Foot  
240 position terminal pins (0.8mm centers, 18x18 array) to SMT solder balls (BGA type). Pin assignment 1:1.

**Tolerances:** diameters ± 0.03mm [± 0.001"], PCB perimeters ± 0.13mm [± 0.005"], PCB thicknesses ± 0.18mm [± 0.007"], pitches (from true position) ± 0.08mm [± 0.003"], all other tolerances ± 0.13mm [± 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>SF-BGA240L-B-61F Drawing</b>	Status: Released	Scale: 6:1	Rev: B
<p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: A. Evans		Date: 5/28/09
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